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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/604,650	08/07/2003	Yi-Chuan Ding	9246-US-PA	1649
31561	7590 12/09/200	ı	EXAMINER	
JIANQ CH 7 FLOOR-1	YUN INTELLECTU	LE, DUNG ANH		
	ROOSEVELT ROAD, SECTION 2			PAPER NUMBER
	100		2818	
			DATE MAILED: 12/09/2004	4

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)	
Office Action Commence	10/604,650	DING ET AL.	
Office Action Summary	Examiner	Art Unit	
	DUNG A LE	2818	
The MAILING DATE of this communication appeared for Reply	ppears on the cover sheet	with the correspondence add	ress
A SHORTENED STATUTORY PERIOD FOR REP THE MAILING DATE OF THIS COMMUNICATION - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a re - If NO period for reply is specified above, the maximum statutory perio - Failure to reply within the set or extended period for reply will, by statu Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	I. 1.136(a). In no event, however, may sply within the statutory minimum of t d will apply and will expire SIX (6) Marte, cause the application to become	a reply be timely filed hirty (30) days will be considered timely. ONTHS from the mailing date of this com ABANDONED (35 U.S.C. § 133).	nmunication.
Status			
1)☐ Responsive to communication(s) filed on 2a)☐ This action is FINAL. 2b)☒ Th 3)☐ Since this application is in condition for allow closed in accordance with the practice under	nis action is non-final. vance except for formal ma	• •	merits is
Disposition of Claims			
4)	rawn from consideration.		
Application Papers			
9) The specification is objected to by the Examination 10) The drawing(s) filed on <u>07 August 2003</u> is/are Applicant may not request that any objection to the Replacement drawing sheet(s) including the correction. The oath or declaration is objected to by the least or the second s	e: a) accepted or b) accepted or b) accepted or b) accepted in abey ection is required if the drawing.	vance. See 37 CFR 1.85(a). ng(s) is objected to. See 37 CFF	R 1.121(d).
Priority under 35 U.S.C. § 119			
12) △ Acknowledgment is made of a claim for foreign a) △ All b) ☐ Some * c) ☐ None of: 1. △ Certified copies of the priority docume 2. ☐ Certified copies of the priority docume 3. ☐ Copies of the certified copies of the priority docume application from the International Bure * See the attached detailed Office action for a list	nts have been received. nts have been received in iority documents have been eau (PCT Rule 17.2(a)).	Application No en received in this National S	Stage
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0 Paper No(s)/Mail Date	Paper N	w Summary (PTO-413) lo(s)/Mail Date of Informal Patent Application (PTO-)le 152)

DETAILED ACTION

Priority

Acknowledge is made of applicants' claim for foreign priority base on an application 91118368 filed in TAIWAN on 8/15/2002.

It is noted that Applicants have filled a certified copy of said application as required by U.S.C 119, which papers have been placed of record in the file.

Oath/Declaration

The oath/declaration filed on 8/7/2003 is acceptable.

Election/Restriction

Examiner confirms that Applicants elected to prosecute Claims 1-9 and have cancelled Claims 10-25 without prejudice.

Specification

The specification is objected to for the following reason:

The title of the invention is not descriptive.

A new title is required that is clearly indicative of the invention to which the claims are directed (see MPEP § 606.01).

Note that, the claims are directed to semiconductor device instead of to a method of making a semiconductor device

The specification has been checked to the extent necessary to determine the presence of all possible minor errors. However, the applicant's cooperation is requested in correcting any errors of which applicant may become aware in the specification.

Claim Rejections

Set of claims 1-5

Claims 1- 5 are rejected under 35 USC 102 (e) as being anticipated by Tsai et al. (US 2003/01849979 A1)

Tsai et al. teaches a substrate, comprising:

a dielectric structure; an interconnection structure 120 interlacing inside the dielectric structure (figs. 1 and 2C); and a solder mask 12 covering the dielectric structure, wherein the solder mask 12 has a coefficient of thermal expansion

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substantially equal to the dielectric structure contacting the solder mask [0012] to [0013].

Regarding claim 2, wherein the material of the solder mask is epoxy resin [0013].

Regarding claim 3, is bismaleimide-triazine [0013].

Regarding claim 4, wherein the solder mask 12 (fig. 1) further covers the interconnection structure 120, the solder mask having at least one opening to expose the interconnection structure 120.

Regarding claim 5, wherein the solder mask 12 has the same material as the dielectric structure contacting the solder mask [0013].

Set of claims 6-9.

Claims 6-8 are rejected under 35 USC 102 (b) as being anticipated by Ts Markovich et al. (5665526)

Markovich et al. disclose a substrate, comprising: a dielectric structure; an interconnection structure interlacing inside the dielectric structure; and a solder mask covering the dielectric structure (col 1, lines 35-45), wherein the glass

transition temperature of the material used for manufacturing the solder mask is over 200 degree C (col 2, lines 60-65).

Regarding claim 7, wherein the solder mask further covers the interconnection structure, the solder mask having at least one opening to expose the interconnection structure (col 1, lines 25-30).

Regarding claim 8, wherein the material of the solder mask is epoxy resin (col 3, line 5).

Claim 9 is rejected under 35 U.S.C. 103 (a) as being unpatentable over Markovich et al. in view of Tsai et al. (US 2003/0184979).

Markovich et al. discloses the claimed invention as applied to claim 6, except for the material of the solder mask is bismaleimide-triazine as cited in current claim.

Tsai teaches the material of the solder mask is bismaleimide-triazine in paragraph [0013].

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to form the solder mask is bismaleimide-triazine in Markovich et al. 's device, in order to improve with its electricity and reduce in its moisture absorbability, thereby bettering overall reliability of the circuit board [0010].

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When responding to the office action, Applicants' are advice to provide the examiner with the line numbers and page numbers in the application and/or references cited to assist the examiner to locate the appropriate paragraphs.

A shortened statutory period for response to this action is set to expire 3 (three) months and 0 (zero) day from the day of this letter. Failure to respond within the period for response will cause the application to become abandoned (see M.P.E.P 710.02(b)).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Dung A. Le whose telephone number is (571) 272-1784. The examiner can normally be reached on Monday-Tuesday and Thursday 6:00am- 4:00 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Nelms can be reached on (571) 272-1787. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 872-9306 for regular communications and (703) 872-9306 for After Final communications.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you

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have questions on access to the Private PAIR system, contact the Electronic Business

Center (EBC) at 866-217-9197 (toll-free).

DUNG A. LE Primary Examiner Art Unit 2818

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